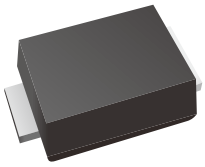
LTS3AE THRU LTS3ME

Surface Mount General Rectifier



Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0

Functional Diagram

Mechanical Data

- **Case**: JEDEC SMBF molded plastic body
- **Polarity**: Color band denotes cathode end
- **Mounting Position**: Any
- **Weight**: 57mg / 0.002oz
- **Terminals**: Solder plated, solderable per MIL-STD-750,Method 2026
- **Marking**:S3A~S3M

Maximum Ratings and Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	Symbols	LTS3AE	LTS3BE	LTS3DE	LTS3GE	LTS3JE	LTS3KE	LTS3ME	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_c = 115 °C	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	80							A
Maximum Instantaneous Forward Voltage at 3 A	V_F	1.1							V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 150							μA
Typical Junction Capacitance (1)	C_j	35							pF
Typical Thermal Resistance (2)	$R_{\theta JA}$ $R_{\theta JC}$	45 15							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2”(5.0x5.0mm) copper pad areas

Ratings and characteristics Curves

Fig.1 Forward Current Derating Curve

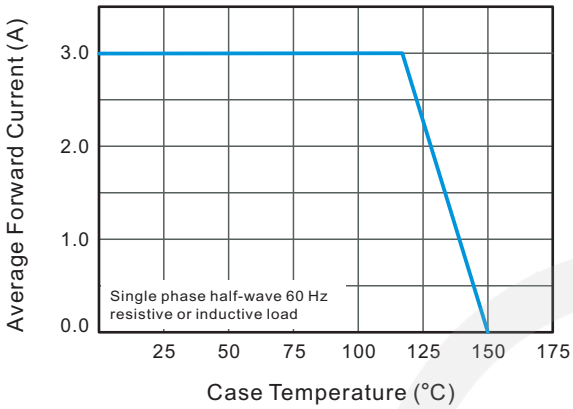


Fig.2 Typical Reverse Characteristics

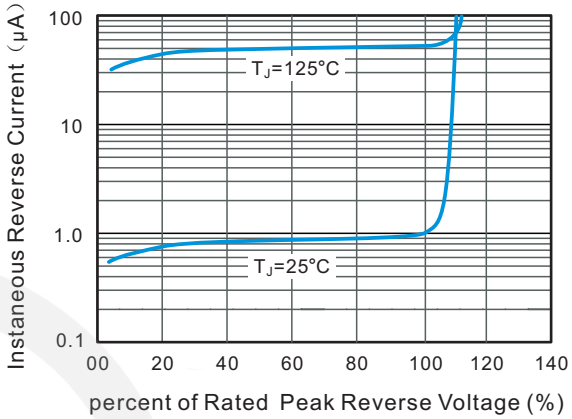


Fig.3 Typical Forward Characteristic

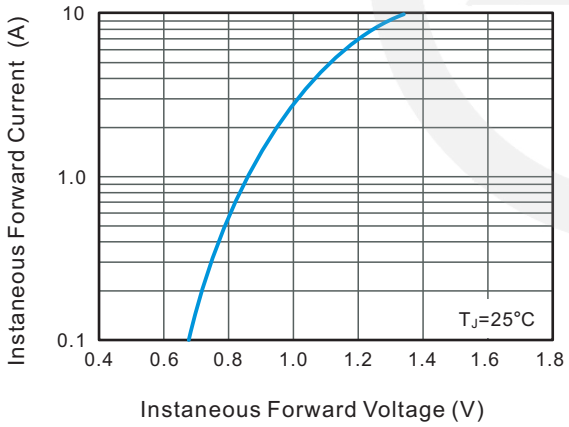


Fig.4 Typical Junction Capacitance

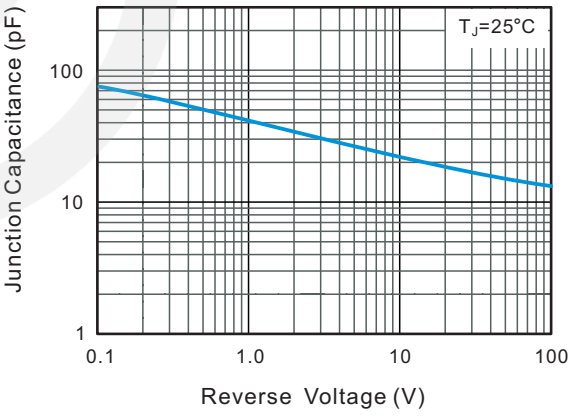
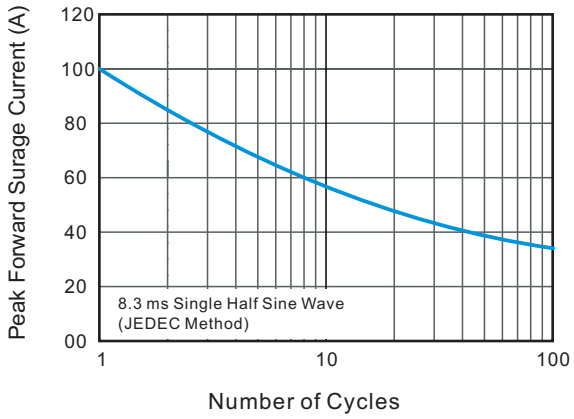
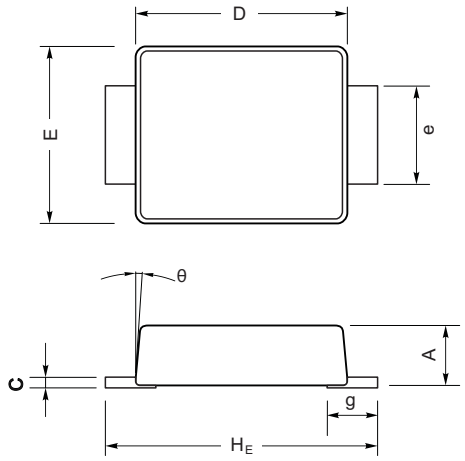


Fig.6 Maximum Non-Repetitive Peak Forward Surage Current

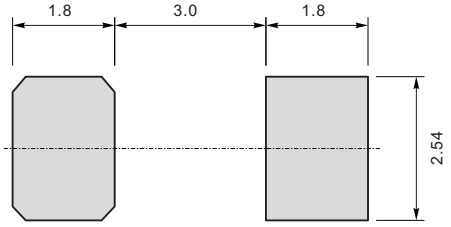


SMBF Package Outline



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.10	1.30
C	0.18	0.26
D	4.20	4.40
E	3.50	3.70
e	1.90	2.20
H_E	5.10	5.50
θ	0.12	

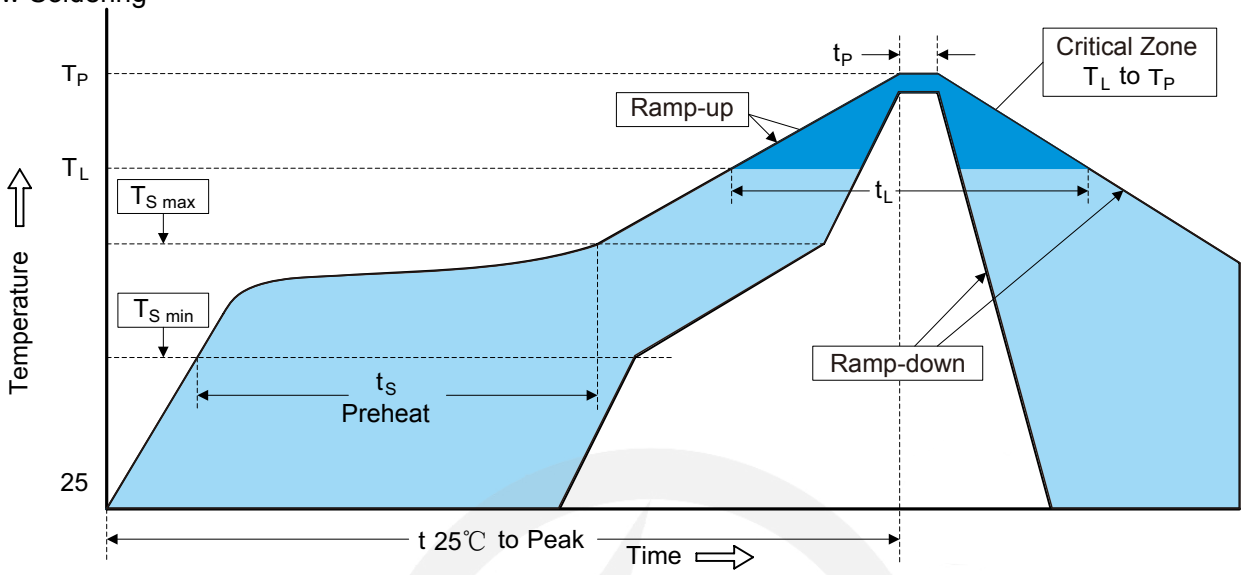
SMBF Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm
3.The pad layout is for reference purpose only.

Recommended Soldering Conditions

Reflow Soldering

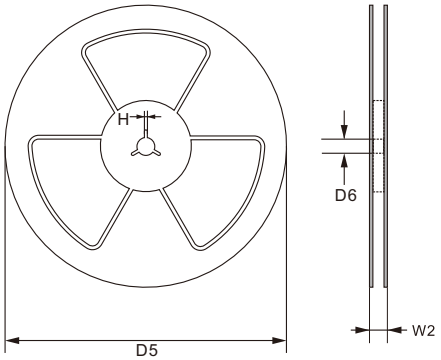


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3℃/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_S)	 150℃ 200℃ 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	 3℃/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	 217℃ 60-150 seconds
Peak Temperature (T_P)	260℃
Time within 5℃ of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8 minutes max.

Packaging

13” Reel



D5	Φ330.0±2.0
D6	Φ13.5±0.5
H	2.5±1.0
W2	16.0±2.0
Quantity: 5000PCS	